

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

**Inventors:** Smith et al.

**Patent No.:** 6,951,137 B2

**Issued:** October 4, 2005

**For:** SYSTEM AND METHOD FOR  
MEASURING BENDING IN A PIN  
MEMBER

**Attorney Docket No.:** 2507-5740US

**VIA ELECTRONIC FILING**

**March 11, 2009**

**REQUEST FOR CERTIFICATE OF CORRECTION OF PATENT  
OFFICE MISTAKES (37 C.F.R. § 1.322)**

Attn.: Certificate of Corrections Branch  
Commissioner for Patents  
P.O. Box 1450  
Alexandria, VA 22313-1450

Sir:

It is noted that several errors appear in this patent of a typographical nature. These errors are due to mistakes in printing on the part of the U.S. Patent and Trademark Office, and occurred through no fault of the Applicants. A certificate of correction in the form attached hereto is requested.

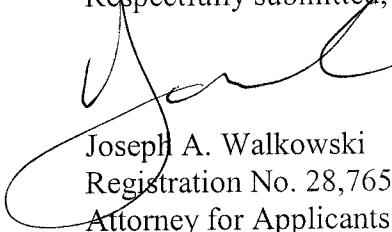
Please note that an Amendment Pursuant to 37 C.F.R. § 1.312(a) (copy enclosed) was filed concurrently with the issue fee on February 16, 2005, but the amendments contained therein were apparently not completely included before issuance of the patent. Attached is a copy of the previously filed Amendment Pursuant to 37 C.F.R. § 1.312(a) and the date-stamped postcard, acknowledging receipt by the PTO, to provide proof of such filing. We have included subject matter of this amendment on the attached PTO/SB/44 being suitable for printing.

Please send the Certificate to:

Name: Joseph A. Walkowski  
Address: TraskBritt  
P.O. Box 2550  
Salt Lake City, Utah 84110

Attached hereto is Form PTO/SB/44, which is suitable for printing.

Respectfully submitted,



Joseph A. Walkowski

Registration No. 28,765

Attorney for Applicants

TRASKBRITT, PC

P.O. Box 2550

Salt Lake City, Utah 84110-2550

Telephone: 801-532-1922

Date: March 11, 2009

JAW/df/slm

Attachments: PTO/SB/44

Copy of Amendment Pursuant to 37 C.F.R. § 1.312(a)

Copy of date-stamped postcard

Document in ProLaw

**UNITED STATES PATENT AND TRADEMARK OFFICE**  
**CERTIFICATE OF CORRECTION**

PATENT NO. : 6,951,137 B2

Page 1 of 4

APPLICATION NO. : 09/897,003

ISSUE DATE : October 4, 2005

INVENTOR(S) : Douglas E. Smith; Peter D. Totman; Randy L. Everton; Paul A. St. Jean; Marvin D. Bunderson; Mark R. Eggett; and Randy L. Borgstrom

It is certified that an error appears or errors appear in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

**In the drawings:**

In FIG. 12,	delete reference numerals 1072, 1076, 1082, 1092 and associated lead lines
In FIG. 14,	delete reference numerals 1072, 1082, 1084, 1092 and associated lead lines
In FIG. 15,	delete reference numerals 1072, 1082, 1092 and associated lead lines

**In the specification:**

COLUMN 16, LINE 33,	change "2116" to --1116--
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MAILING ADDRESS OF SENDER (Please do not use customer number below):

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 TRASKBRITT  
 230 South 500 East, Suite 300  
 Salt Lake City, Utah 84102 USA

This collection of information is required by 37 CFR 1.322, 1.323, and 1.324. The information is required to obtain or retain a benefit by the public which is to file (and by the USPTO to process) an application. Confidentiality is governed by 35 U.S.C. 122 and 37 CFR 1.14. This collection is estimated to take 1.0 hour to complete, including gathering, preparing, and submitting the completed application form to the USPTO. Time will vary depending upon the individual case. Any comments on the amount of time you require to complete this form and/or suggestions for reducing this burden, should be sent to the Chief Information Officer, U.S. Patent and Trademark Office, U.S. Department of Commerce, P.O. Box 1450, Alexandria, VA 22313-1450. DO NOT SEND FEES OR COMPLETED FORMS TO THIS ADDRESS.  
**SEND TO: Attention Certificate of Corrections Branch, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450.**

*If you need assistance in completing the form, call 1-800-PTO-9199 and select option 2.*

**UNITED STATES PATENT AND TRADEMARK OFFICE**  
**CERTIFICATE OF CORRECTION**

PATENT NO. : 6,951,137 B2

Page 2 of 4

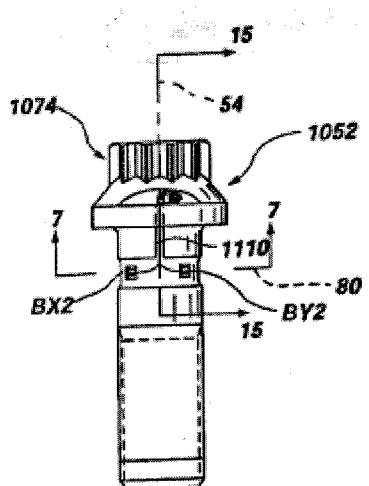
APPLICATION NO. : 09/897,003

ISSUE DATE : October 4, 2005

INVENTOR(S) : Douglas E. Smith; Peter D. Totman; Randy L. Everton; Paul A. St. Jean; Marvin D. Bunderson; Mark R. Eggett; and Randy L. Borgstrom

It is certified that an error appears or errors appear in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

**Replace FIG. 12 with the following amended figure:**



**FIG. 12**

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**UNITED STATES PATENT AND TRADEMARK OFFICE**  
**CERTIFICATE OF CORRECTION**

PATENT NO. : 6,951,137 B2

Page 3 of 4

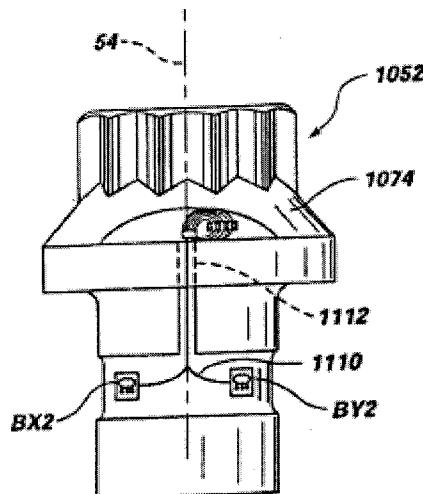
APPLICATION NO. : 09/897,003

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INVENTOR(S) : Douglas E. Smith; Peter D. Totman; Randy L. Everton; Paul A. St. Jean; Marvin D. Bunderson; Mark R. Eggett; and Randy L. Borgstrom

It is certified that an error appears or errors appear in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

**Replace FIG. 14 with the following amended figure:**



**FIG. 14**

MAILING ADDRESS OF SENDER (Please do not use customer number below):

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 Salt Lake City, Utah 84102 USA

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**CERTIFICATE OF CORRECTION**

PATENT NO. : 6,951,137 B2

Page 4 of 4

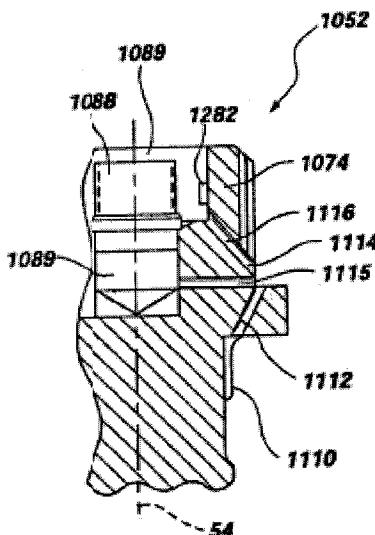
APPLICATION NO. : 09/897,003

ISSUE DATE : October 4, 2005

INVENTOR(S) : Douglas E. Smith; Peter D. Totman; Randy L. Everton; Paul A. St. Jean; Marvin D. Bunderson; Mark R. Eggett; and Randy L. Borgstrom

It is certified that an error appears or errors appear in the above-identified patent and that said Letters Patent is hereby corrected as shown below:

**Replace FIG. 15 with the following amended figure:**



**FIG. 15**

MAILING ADDRESS OF SENDER (Please do not use customer number below):

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 Salt Lake City, Utah 84102 USA

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THE PATENT & TRADEMARK OFFICE MAILROOM DATE  
STAMPED HEREON IS AN ACKNOWLEDGEMENT THAT ON THIS  
DATE THE PATENT & TRADEMARK OFFICE RECEIVE

Transmittal Letter (2 pages, in duplicate); Part B - Issue Fee  
Transmittal (1 page); Check No. 21363 in the amount of \$1,730.00;  
Amendment Pursuant to 37 C.F.R. § 1.312(a) (27 pages); Attached  
Replacement Sheet of Drawings (1 sheet) and Annotated Sheet  
Showing Changes Made (1 sheet); and Fee Addressee for Receipt  
of PTO Notices Relating to Maintenance Fees (2 pages)

RECEIVED

FFB 2 2 2005

TRASKBRITT, P.C.

Invention: SYSTEM AND METHOD FOR MEASURING  
BENDING IN A PIN MEMBER  
Applicant(s): Smith et al.  
Filing Date: July 2, 2001  
Serial No.: 09/897,003  
Date Sent: February 16, 2005 via Express Mail Label No.  
Docket No.: 2507-5740US  
KLD/njj:dd



**PATENT**

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**In re Application of:**

Smith et al.

**Serial No.:** 09/897,003

**Filed:** July 2, 2001

**For:** METHOD AND APPARATUS FOR  
MEASURING BENDING IN A PIN  
MEMBER (as amended)

**Confirmation No.:** 1140

**Examiner:** L. Martir

**Group Art Unit:** 2855

**Attorney Docket No.:** 2507-5740US

**Notice of Allowance Mailed:**

November 18, 2004

Express Mail Mailing Label No.: EL 994825454 US

Date of Deposit with USPS: February 16, 2005

Person making Deposit: Steve Wong

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Commissioner for Patents  
P.O. Box 1450  
Alexandria, Virginia 22313-1450

Sir:

Please amend the above-referenced application as follows:

**Amendments to the Title Page** appear on page 3 of this paper.

**Amendments to the Specification** begin on page 4 of this paper.

**Amendments to the Claims** are reflected in the listing of claims which begins on page 16 of this paper.

**Amendments to the Drawings** appear on page 26 of this paper and include both an attached replacement sheet and an annotated sheet showing changes.

Remarks begin on page 27 of this paper.

An Appendix including amended drawing figures is attached.

**ON THE TITLE PAGE:**

Corrections to the list of inventors have been made to conform with the Original Assignment and the Official Filing Receipt as follows:

**Inventors:**

Douglas E. Smith

Peter D. Totman

Randy L. Everton

~~Paul A. St. John~~Paul A. St. Jean

Marvin D. Bunderson

Mark R. Eggett

Randy L. Borgstrom

IN THE SPECIFICATION:

Please amend paragraph number [0008] as follows:

[0008] To achieve the foregoing objects, and in In accordance with the purposes of the invention as embodied and broadly described in this document, an instrumented pin member is provided. The instrumented pin member comprises a pin member body disposed about a pin member axis. The pin member body comprises a bending portion. The instrumented pin member further comprises a sensing device positioned at the pin member body within the bending portion for sensing a bending strain in the bending portion exclusive of a net axial strain and for outputting a sensor measurement signal representative of the bending strain. In addition, the instrumented pin member comprises a sensor measurement signal output device for outputting the sensor measurement signal from the sensing device.

Please amend paragraph number [0009] as follows:

[0009] Preferably Preferably, but optionally, the sensing device senses components of the bending strain in the bending portion along an x axis and a y axis, wherein the x-axis-x axis and the y axis are orthogonal to the pin member axis and to each other.

Please amend paragraph number [0010] as follows:

[0010] The pin member body may comprise a bolt, a pin, a screw, an axle, and the like. Preferably Preferably, but optionally, the pin member body has a cylindrical shape about the pin member axis. The pin member head preferably includes a head, and the bending portion is adjacent to the head.

Please amend paragraph number [0016] as follows:

[0016] The instrumented pin member preferably but optionally preferably, but optionally, also comprises a switching device operatively coupled to the sensing device for switching between an axial stress measurement configuration and a bending stress measurement configuration. The switching device may comprise a solid state switching circuit. The switching device may be and preferably and, preferably, positioned at the pin member head. In a presently preferred embodiment, the pin member head includes an external surface and a notch disposed in the external surface, and the switching device is mounted to the external surface. The pin member head also may comprises a head including a head cavity, and the switching device may be positioned at the pin member head cavity.

Please amend paragraph number [0018] as follows:

[0018] Where the sensing device comprises a pair of bridges, each having an axial stress measurement configuration and a bending stress measurement configuration, the switching device preferably comprises a switch operatively coupled to the pair of bridges, for switching the pair of bridges between the axial stress measurement configuration and the bending stress measurement configuration. Preferably-Preferably, but optionally, the switching device switches the pair of bridges to the bending stress measurement configuration substantially simultaneously.

Please amend paragraph number [0020] as follows:

[0020] Preferably-Preferably, but optionally, the system comprises a switching device operatively coupled to the sensing device for switching the sensing device in and out of a bending stress mode. The system preferably but optionally preferably, but optionally, comprises a plurality of the instrumented pin members.

Please amend paragraph number [0044] as follows:

[0044] Optionally Optionally, but preferably, one or more instrumented pin members, e.g., as described more fully herein, can be substituted at joint 36 for selected ones of noninstrumented pin members 46 so that when motor 30 is fired, the instrumentation, again, for example, as described herein, can measure bending stresses within these instrumented pin members, i.e., at joint 36. A plurality of these instrumented pin members may be disposed, for example, by uniformly distributing them around joint 36, or in other predetermined arrangements. The bending stress data, and in some instances other data as well, from the instrumented pin member or pin members can be used to simulate, estimate or otherwise predict the same stresses that are occurring in the normal operational, noninstrumented pin members and at the joint itself.

Please amend paragraph number [0046] as follows:

[0046] System 50 also comprises a control box 55, a preamplifier ("preamp") or data conditioner 56, a storage device 58, e.g., a hard drive on a computer, a processor 60, e.g., such as the processor of a commercially-available personal computer or small business computer, and a display monitor 62. A data recording device 64 such as a strip chart recorder or other device useful for recording data from the instrumented pin members may be used as well. In presently preferred embodiments, the system comprises a computer, preferably having a 12 bit range or above, and a control box 55. Control box 55 is positioned between the pin members 52 and preamp 56 and preferably and, preferably, is located as close to the pin members as is practicable under the circumstances with respect to the electrical connections. Control box 55 is electrically coupled to the sensors, as described below, and receives signals, e.g., analog sensor measurement output signals, from them. It includes an oscillator as described further below, an and an optoisolator for assisting in isolating the digital signals from the analog signals. Control box 55 is capable of operating in three modes, i.e., a pure axial measurement mode, a pure bending mode, and a switching mode in which it alternates between an axial stress measurement mode and a bending stress measurement mode.

Please amend paragraph number [0051] as follows:

[0051] The pin member body 70 according to this aspect of the invention also comprises a bending portion. This portion of the pin member body undergoes bending stresses and experiences associated strains under normal operating conditions for the joint and the device of which it forms a part, e.g., the rocket motor. The bending portion portion, as referred to herein herein, need not constitute the entire portion of the pin member that is subject to bending stresses or strains. It does, however, comprise at least a portion of the pin member body that is subject to bending stress which, in many cases, will include the entire member. The "bending portion," as the term is used herein, refers to any area or portion of the pin member 52 that is suitable for measurement of bending moments under the application and circumstances. Preferably, the bending portion is selected to be a region of the pin member that experiences substantial strain relative to other parts of the pin member during normal operating conditions, and which is representative of the strain occurring in the entire portion of the pin member that is subject to such bending forces. The bending portion, in many instances, will comprise the area immediately adjacent to the pin member head.

Please amend paragraph number [0053] as follows:

[0053] Pin member 52 includes a radially chamfered groove 92 in bending portion 90. It preferably is positioned on shank 72 below the base portion 84 of head 74. The positioning of the groove preferably is selected so that unwanted contributions from localized effects at and around the base portion 84 of head 74 are avoided, and so that there is no unwanted interference with the head during installation, maintenance, etc. This groove 92 may be disposed in the shank portion, for example, by lathing pin member 52. The depth of groove 92 radially with respect to perimeter 78 of shank 72 and the length along the longitudinal pin member axis 54 (z axis) may be selected to house and accommodate sensors and associated circuitry, as will be described herein below. In the presently preferred embodiments, and using the sensors as described herein below, the depth of groove 92 is approximately equal to the depth of the minor thread diameter of the shank threads. Preferably, it is no smaller than the thread root, e.g., to avoid adverse effects on the strength of the pin member. Groove 92 is shown in highly exaggerated depth in Fig. 7 to better illustrate.

Please amend paragraph number [0054] as follows:

[0054] Further, in accordance with this aspect of the invention, the instrumented pin member includes a sensing device positioned at the pin member body within the bending portion for sensing a bending strain in the bending portion exclusive of a net axial strain and for outputting a sensor measurement signal representative of the bending strain. The sensing device senses the bending strain in the bending portion exclusive of a net axial strain in the sense that it is capable of sensing bending strains, and thus strains and, thus, bending moments, in the bending portion of the pin member, without the measurement being adversely affected by a net axial strain, i.e., without adverse interference or effects of a net tension or compression of the pin member. This may be done, and in the presently preferred embodiments is done, using, among other things, a sensing device wherein such net axial strain components are canceled out.

Please amend paragraph number [0056] as follows:

[0056] The sensing device device, according to this aspect of the invention-invention, preferably comprises first and second x axis sensor elements for measuring the bending strain along the x axis and first and second y axis sensor elements for measuring the bending strain along the y axis. The sensor elements preferably lie in a plane orthogonal with respect to the pin member longitudinal axis, for example, such as plane 80. In presently preferred embodiments, each of the first and second x and y axis sensor elements comprises an axial sensor for sensing strain in a pin member axial direction corresponding to the pin member axis and a tangential sensor for sensing strain in a direction tangential to the shank perimeter. The tangential direction in these embodiments involves a tangent to shank perimeter, or more accurately to the slightly smaller perimeter of groove 92 in planes orthogonal to longitudinal pin member axis 54 where the sensors reside, for example, as identified in Fig. 7 by reference number 94. Tangential direction 94 thus represents tangent vectors to shank perimeter 78, or to the perimeter of groove 92, and thus constitutes a circumferential tangent to the shank or groove circumference. Given that radial depth of groove 92 in many applications will be quite small relative to the shank diameter, the perimeter for groove 92 and the shank perimeter at a given radial location will be essentially the same.

Please amend paragraph number [0057] as follows:

[0057] The sensing device device, according to the preferred embodiments embodiments, will now be described. In these illustrative embodiments, a sensing device is provided which comprises first and second x axis sensor elements BX1 and BX2, respectively, and first and second y axis sensor elements BY1 and BY2, respectively (shown in Fig. 7). Each of the sensor elements lies on the perimeter of groove 92, and thus essentially at shank perimeter 78, all within plane 80. Sensor elements BX1 and BX2 lie along the x axis on opposite sides of shank perimeter 78, and sensor elements BY1 and BY2 lie on the y axis on opposite sides of shank perimeter 78. The x axis sensor elements thus elements, thus, are disposed at 90 degrees with respect to the y axis sensor elements. Each of the sensor elements BX1, BX2, BY1 and BY2 comprises a pair of sensors including an axial or "tension" sensor, denoted by a "T," and a tangential or "compression" sensor, denoted by a "C" after the sensor element designation, e.g., BX1(T) or BX1(C).

Please amend paragraph number [0061] as follows:

[0061] The sensing device device, according to presently preferred embodiments of the invention invention, comprises a bridge assembly for receiving the sensor measurement signals and making necessary or appropriate conversions to measure bending stress. In these embodiments, the bridge assembly can assume an axial stress measurement configuration and a bending stress measurement configuration. The bridge assembly may comprise a single bridge, but bridge but, preferably and optionally optionally, comprises a pair of bridges, which still further preferably comprises an x axis bridge and a y axis bridge. A single bridge can be useful in detecting bending strains but typically will not include directional information, or will measure only components of strain along a single plane. In accordance with the presently preferred embodiments, the sensing device comprises a pair of bridges, specifically an x axis bridge 150 and a y axis bridge 250, for example, as shown in Figs. 8 and 9. In these embodiments, each of the bridges 150 and 250 comprises a full active Wheatstone strain gage bridge.

Please amend paragraph number [0062] as follows:

[0062] The x axis ~~bridge~~bridge, in preferred ~~embodiments~~embodiments, comprises a left side and a right side. The left x axis bridge side comprises first and second positions and the right x axis bridge side comprises first and second positions. The first position of the left x axis bridge side and the first position of the right x axis bridge side comprise what may be termed a "first aligned x axis configuration," and the second position of the left x axis bridge side and the second position of the right x axis bridge side comprise what may be termed a "second aligned x axis configuration." Similarly, the y axis ~~bridge~~bridge, in preferred ~~embodiments~~embodiments, comprises a left side and a right side. The left y axis bridge side comprises first and second positions and the right y axis bridge side comprises first and second positions. The first position of the left y axis bridge side and the first position of the right y axis bridge side comprise what may be termed a "first aligned y axis configuration," and the second position of the left y axis bridge side and the second position of the right y axis bridge side comprise what may be termed a "second aligned configuration." The first aligned x axis configuration corresponds to the first aligned y axis configuration, and the second aligned x axis configuration corresponds to the second aligned y axis configuration, as will be illustrated further herein below.

Please amend paragraph number [0068] as follows:

[0068] The ~~system~~system, comprising instrumented pin members 52 with sensors as described and with bridges as shown in Fig. 8Fig. 8, cancels net axial strains and, therefore, measures bending moments. In presently preferred embodiments, however, it is desired and preferred that each instrumented pin member 52 also be configured to operate in an axial stress measurement mode, in which net axial stress is ~~measure~~measured exclusive of bending moments, and a bending stress measurement mode, in which bending stress is measured exclusive of net axial stresses, and ~~preferably~~stresses and, ~~preferably~~exclusive of torsional stresses as well.

Please amend paragraph number [0069] as follows:

[0069] To implement this feature, the sensing device preferably comprises an axial stress measurement configuration, a bending stress measurement configuration, and a switching device operatively coupled to the sensing device for switching between them. The pin member 52, when placed in the axial stress measurement configuration and ~~operated-operated~~, as described herein, is in the axial measurement mode. When pin member 52 is placed in the bending stress measurement configuration and operated, it is in the bending stress measurement mode.

Please amend paragraph number [0070] as follows:

[0070] The sensing device, according to the presently preferred embodiments as disclosed herein, is in the bending stress measurement mode when the axial sensors of the first and second x axis sensor elements are in one of the first aligned x axis configuration and the second aligned x axis configuration, and the axial sensors of the first and second y axis sensor elements are in one of the first aligned y axis configuration and the second aligned y axis configuration. Similarly, the sensing device is in the bending stress measurement configuration when the tangential sensors of the first and second x axis sensor elements are in one of the first aligned x axis configuration and the second aligned x axis configuration, and the tangential sensors of the first and second y axis sensor elements are in one of the first aligned y axis configuration and the second aligned y axis configuration.

Please amend paragraph number [0074] as follows:

[0074] A switching device ~~280~~ device 280, according to the presently preferred embodiments for this aspect of the invention invention, comprises a pair of identical switching circuits 282, one of which is shown in Fig. 10. Switching circuit 282 comprises a pair of 4-ohm complementary metal oxide semiconductor (CMOS) SPDT switches 300 and 400, each of which comprises a pair of field effect transistors (FET). In these preferred embodiments, switches 300 and 400 comprise an Advanced Micro Devices Model ADG719BRM switch, commercially available from Advanced Micro Devices of Sunnyvale, California. Switches 300 and 400 function to reverse the polarity of the right side of bridges 150 and 250, thereby effectively reversing the positions of the sensors at the first and second positions of the right sides of the respective bridges 150 and 250, i.e., between the bridge assembly configurations shown in Figs. 8 and 9. Switch 300 provides the switched coupling of the bridge line providing voltage  $+XF$ , and switch 400 provides the switched coupling of the bridge line providing voltage  $-XF$ , as shown in Figs. 8 and 9. The switches selected for switching circuits 282 preferably have a very low impedance when in the "ON" state and have an extremely high impedance when in the "OFF" state.

Please amend paragraph number [0078] as follows:

[0078] A switching signal source 288 is coupled to the line 284 providing signal BSIG for generating the switching signal thereby provided. Preferably, the switching signal comprises a periodic signal that causes the switching circuitry to switch states periodically. It should be noted, however, that this is not necessarily limiting, and that other switch timing relationships are possible. Switching signal source 288 in the preferred embodiments comprises an oscillator that provides a conditioned, periodic square wave for selectively and periodically triggering switches 300 and 400. Switching signal source 288-288, according to the presently preferred embodiment, is physically located in control box 55 (Fig. 2). Switching signal source 288 also may include circuitry for shaping the signal signal, as is appropriate for the particular switches used. A frequency divider, for example, may be used to better insure that the switching transistor is precise, e.g., by building up the leading or trailing edge of the square wave. In the presently preferred embodiments, switching circuits 282, under the control of the switching signal BSIG, cause each pin member to switch states between the axial stress measurement configuration and the bending stress configuration at a desired rate, depending upon the application. This switching rate may vary from 0 Hz (steady axial or bending mode) to 40 to 50 KHz and possibly higher. Preferred ranges include 10 Hz to 2 KHz, and KHz and, more preferably, about 110 to 500 Hz. Higher frequencies such as 30 to 40 KHz may be useful, for example, when investigating mechanical shock or shock wave phenomena. Natural physical limits on the switching frequency may occur, depending on the circumstance, as will be understood by persons of ordinary skill in the art. Physical limits may be placed, for example, by the impedance of lines coupled to the switches, or by the frequency of the phenomena to be measured.

Please amend paragraph number [0088] as follows:

[0088] The cavity 1089 itself may be made in known fashion, i.e., by machining. With reference to Fig. 15, an angled notch 1116 is provided in head 1074, extending from notch 1112 as previously described and extending to the cavity 1089 of broach 1088. Notch 1116 is sized so that ~~leads 1100~~ ~~leads 1110~~ can pass through it and into cavity 1089. A notch 1115 extends from aperture 1114 into extended portion 1089 of broach 1088. This notch can be useful in gaining access to the cavity 1089, e.g., for placing switching device components, inspecting them, etc.

Please amend paragraph number [0092] as follows:

[0092] The system further includes a data receiving device operatively coupled to the sensor signal output device for receiving the sensor output signal. ~~Preferably~~ Preferably, but optionally, the data receiving device comprises a data processor. It also may comprise a data display, a data recorder, a strip chart recorder, or any other device or collection of devices suitable for receiving, storing, processing and/or displaying or presenting the data embodied in the sensor signal. As implemented in the presently preferred embodiments, the data receiving device comprises the components illustrated in Fig. 2, and as described above.

IN THE CLAIMS:

Claims 6, 8, 32, 36-40 and 43-56 were previously canceled. No claims have been amended herein. All of the pending claims 1 through 56 are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

Listing of Claims:

1. (previously presented) An instrumented pin member, comprising:  
a pin member body disposed about a pin member axis, the pin member body comprising a shank including a shank perimeter lying in a plane orthogonal to the pin member axis and a bending portion; a sensing device positioned at the pin member body within the bending portion for sensing a bending strain in the bending portion exclusive of a net axial strain, and for outputting a sensor measurement signal representative of the bending strain, the sensing device comprising:  
first and second x axis sensor elements configured for measuring the bending strain along an x axis, each of the first and second x axis sensor elements comprising a tangential sensor for sensing strain in a direction tangential to the shank perimeter;  
and  
first and second y axis sensor elements configured for measuring the bending strain along a y axis; and  
a sensor measurement signal output device for outputting the sensor measurement signal from the sensing device.
2. (previously presented) The instrumented pin member as recited in claim 1, wherein the sensing device senses components of the bending strain in the bending portion along an x axis and a y axis, the x axis and the y axis being orthogonal to the pin member axis and to each other.
3. (previously presented) The instrumented pin member as recited in claim 1, wherein the pin member body comprises a bolt.

4. (previously presented) The instrumented pin member as recited in claim 1, wherein the pin member body has a cylindrical shape about the pin member axis.

5. (previously presented) The instrumented pin member as recited in claim 1, wherein:

the pin member body comprises a head; and  
the bending portion is adjacent to the head.

6. (canceled)

7. (previously presented) The instrumented pin member as recited in claim 1, wherein each of the first and second x axis sensor elements further comprises an axial sensor for sensing strain in a pin member axial direction corresponding to the pin member axis.

8. (canceled)

9. (previously presented) The instrumented pin member as recited in claim 1, wherein each of the first and second y axis sensor elements comprises an axial sensor for sensing strain in a pin member axial direction corresponding to the pin member axis.

10. (previously presented) The instrumented pin member as recited in claim 1, wherein

each of the first and second y axis sensor elements comprises a tangential sensor for sensing strain in a direction tangential to the shank perimeter.

<sup>14</sup> 11. (previously presented) The instrumented pin member as recited in claim 1, wherein:  
each of the first and second x axis sensor elements and each of the first and second y axis sensor elements comprises an axial sensor for sensing strain in a pin member axial direction corresponding to the pin member axis;  
and  
each of the first and second y axis sensor elements comprises a tangential sensor for sensing strain in a direction tangential to the shank perimeter.

12. (previously presented) The instrumented pin member as recited in claim 7, wherein the sensing device further comprises:  
an x axis bridge having a left side and a right side, the left x axis bridge side comprising first and second positions and the right x axis bridge side comprising first and second positions; the first position of the left x axis bridge side and the first position of the right x axis bridge side being in a first aligned x axis configuration; and the second position of the left x axis bridge side and the second position of the right x axis bridge side being in a second aligned x axis configuration, the axial sensors of the first and second x axis sensor elements being in one of the first aligned x axis configuration and the second aligned x axis configuration.

13. (previously presented) The instrumented pin member as recited in claim 7, wherein the sensing device further comprises:  
an x axis bridge having a left side and a right side, the left x axis bridge side comprising first and second positions and the right x axis bridge side comprising first and second positions;  
the first position of the left x axis bridge side and the first position of the right x axis bridge side being in a first aligned x axis configuration; and  
the second position of the left x axis bridge side and the second position of the right x axis bridge side being in a second aligned x axis configuration; and  
an axial stress measurement configuration and a bending stress measurement configuration, the sensing device being in the bending stress measurement mode when the axial sensors of the first and second x axis sensor elements are in one of the first aligned x axis configuration and the second aligned x axis configuration.

14. (previously presented) The instrumented pin member as recited in claim 13, wherein the sensing device is in the axial stress measurement configuration when the axial sensors of the first and second x axis sensor elements are not in one of the first aligned x axis configuration and the second aligned x axis configuration.

15. (previously presented) The instrumented pin member as recited in claim 1, wherein: the sensing device comprises:  
an x axis bridge having a left side and a right side, the left x axis bridge side comprising first and second positions and the right x axis bridge side comprising first and second positions;  
the first position of the left x axis bridge side and the first position of the right x axis bridge side being in a first aligned x axis configuration; and  
the second position of the left x axis bridge side and the second position of the right x axis bridge side being in a second aligned x axis configuration;  
the tangential sensors of the first and second x axis sensor elements being in one of the first aligned x axis configuration and the second aligned x axis configuration.

16. (previously presented) The instrumented pin member as recited in claim 11, wherein the sensing device comprises:

an x axis bridge having a left side and a right side, the left x axis bridge side comprising first and second positions and the right x axis bridge side comprising first and second positions;

the first position of the left x axis bridge side and the first position of the right x axis bridge side being in a first aligned x axis configuration; and

the second position of the left x axis bridge side and the second position of the right x axis bridge side being in a second aligned x axis configuration; and

an axial stress measurement configuration and a bending stress measurement configuration, the sensing device being in the bending stress measurement configuration when the tangential sensors of the first and second x axis sensor elements are in one of the first aligned x axis configuration and the second aligned x axis configuration.

17. (previously presented) The instrumented pin member as recited in claim 16, wherein the sensing device is in the axial stress measurement configuration when the tangential sensors of the first and second x axis sensor elements are not in one of the first aligned x axis configuration and the second aligned x axis configuration.

18. (previously presented) The instrumented pin member as recited in claim 9, wherein the sensing device comprises:

a y axis bridge having a left side and a right side, the left y axis bridge side comprising first and second positions and the right y axis bridge side comprising first and second positions; the first position of the left y axis bridge side and the first position of the right y axis bridge side being in a first aligned y axis configuration; and

the second position of the left y axis bridge side and the second position of the right y axis bridge side being in a second aligned y axis configuration;

the axial sensors of the first and second y axis sensor elements being in one of the first aligned y axis configuration and the second aligned y axis configuration.

19. (previously presented) The instrumented pin member as recited in claim 18, wherein the sensing device further comprises:

an axial stress measurement configuration and a bending stress measurement configuration, the sensing device being in the bending stress measurement configuration when the axial sensors of the first and second y axis sensor elements are in one of the first aligned y axis configuration and the second aligned y axis configuration.

20. (previously presented) The instrumented pin member as recited in claim 19, wherein the sensing device is in the axial stress measurement configuration when the axial sensors of the first and second y axis sensor elements are not in one of the first aligned y axis configuration and the second aligned y axis configuration.

21. (previously presented) The instrumented pin member as recited in claim 10, wherein the sensing device further comprises:

a y axis bridge having a left side and a right side, the left y axis bridge side comprising first and second positions and the right y axis bridge side comprising first and second positions; the first position of the left y axis bridge side and the first position of the right y axis bridge side being in a first aligned y axis configuration; and the second position of the left y axis bridge side and the second position of the right y axis bridge side being in a second aligned y axis configuration; the tangential sensors of the first and second y axis sensor elements being in one of the first aligned y axis configuration and the second aligned y axis configuration.

22. (previously presented) The instrumented pin member as recited in claim 21, wherein the sensing device further comprises:

an axial stress measurement configuration and a bending stress measurement configuration, the sensing device being in the bending stress measurement configuration when the axial sensors of the first and second y axis sensor elements are in one of the first aligned y axis configuration and the second aligned y axis configuration.

23. (previously presented) The instrumented pin member as recited in claim 22, wherein the sensing device is in the axial stress measurement configuration when the axial sensors of the first and second y axis sensor elements are not in one of the first aligned y axis configuration and the second aligned y axis configuration.

24. (previously presented) The instrumented pin member as recited in claim 11, wherein the sensing device further comprises:  
an x axis bridge having a left side and a right side, the left x axis bridge side comprising first and second positions and the right x axis bridge side comprising first and second positions; the first position of the left x axis bridge side and the first position of the right x axis bridge side being in a first aligned x axis configuration; and the second position of the left x axis bridge side and the second position of the right x axis bridge side being in a second aligned x axis configuration;  
the axial sensors of the first and second x axis sensor elements being in one of the first aligned x axis configuration and the second aligned x axis configuration, and the tangential sensors of the first and second x axis sensor elements being in the other of the first aligned x axis configuration and the second aligned x axis configuration; and  
a y axis bridge having a left side and a right side, the left y axis bridge side comprising first and second positions and the right y axis bridge side comprising first and second positions; the first position of the left y axis bridge side and the first position of the right y axis bridge side being in a first aligned y axis configuration; and the second position of the left y axis bridge side and the second position of the right y axis bridge side being in a second aligned y axis configuration;  
the axial sensors of the first and second y axis sensor elements being in one of the first aligned y axis configuration and the second aligned y axis configuration, and the tangential sensors of the first and second y axis sensor elements being in the other of the first aligned y axis configuration and the second aligned y axis configuration.

25. (previously presented) The instrumented pin member as recited in claim 1, wherein the sensing device further comprises a bridge assembly having an axial stress measurement configuration and a bending stress measurement configuration.

26. (previously presented) An instrumented pin member, comprising:  
a pin member body disposed about a pin member axis, the pin member body comprising a bending portion;  
a sensing device positioned at the pin member body within the bending portion for sensing a bending strain in the bending portion exclusive of a net axial strain, and for outputting a sensor measurement signal representative of the bending strain;  
a sensor measurement signal output device for outputting the sensor measurement signal from the sensing device; and  
a switching device operatively coupled to the sensing device for switching between an axial stress measurement configuration and a bending stress measurement configuration.

27. (previously presented) The instrumented pin member as recited in claim 26, wherein the switching device comprises a solid state switching circuit.

28. (previously presented) The instrumented pin member as recited in claim 26, wherein:  
the pin member comprises a head; and  
the switching device is positioned at the pin member head.

29. (previously presented) The instrumented pin member as recited in claim 28, wherein:  
the pin member head includes an external surface and a notch disposed in the external surface; and  
the switching device is mounted to the external surface.

30. (previously presented) The instrumented pin member as recited in claim 26, wherein:

the pin member comprises a head including a head cavity; and  
the switching device is positioned at the pin member head cavity.

31. (previously presented) The instrumented pin member as recited in claim 26, wherein the switching device comprises a periodic switching signal source for providing a periodic switching signal.

32. (canceled)

33. (previously presented) The instrumented pin member as recited in claim 26, wherein:

the sensing device comprises a pair of bridges, each having an axial stress measurement configuration and a bending stress measurement configuration; and  
the switching device comprises a switch operatively coupled to the pair of bridges for switching the pair of bridges between the axial stress measurement configuration and the bending stress measurement configuration.

34. (previously presented) The instrumented pin member as recited in claim 33, wherein the switching device switches the pair of bridges to the bending stress measurement configuration substantially simultaneously.

35. (original) An instrumented pin member, comprising:  
a pin member body disposed about a pin member axis, the pin member body comprising a  
bending portion;  
a sensing device positioned on the pin member body within the bending portion for sensing a  
bending stress in the bending portion during a bending stress measurement mode and for  
outputting a sensor measurement signal;  
a switching device operatively coupled to the sensing device for switching the sensing device in  
and out of the bending stress measurement mode; and  
a sensor signal output device for communicating the sensor measurement signal.

36-40 (canceled)

41. (previously presented) A method for measuring bending at a joint, the method  
comprising:  
disposing an instrumented pin member at the joint, the instrumented pin member comprising a  
pin member body disposed about a pin member axis, the pin member body comprising a  
bending portion;  
sensing a bending strain in the bending portion exclusive of a net axial strain during a bending  
stress measurement mode and outputting a sensor measurement signal, wherein the  
sensing includes switching in and out of the bending stress measurement mode; and  
communicating the sensor measurement signal to a data receiving device.

42. (previously presented) The method as recited in claim 41, wherein the disposing  
of the instrumented pin member comprises disposing a plurality of instrumented pin members at  
the joint so that the instrumented pin members are substantially equally spaced about the joint.

43-56 (canceled)

IN THE DRAWINGS:

The attached sheet of drawings includes changes to FIGS. 12, 14 and 15. This sheet, which includes FIGS. 12-15, replaces the original sheet including FIGS. 12-15.

Specifically, FIG. 12 has been revised to delete the reference numerals 1072, 1076, 1082, 1084 and 1092 with appropriate lead lines (not referenced in specification); FIG. 14 has been revised to delete the reference numerals 1072, 1082, 1084 and 1092 with appropriate lead lines (not referenced in specification); and FIG. 15 has been revised to delete the reference numerals 1072, 1082, and 1092 with appropriate lead lines (not referenced in specification). No new matter has been added.

REMARKS

This amendment corrects errors in the text and drawings. Entry is respectfully solicited.

This amendment is submitted prior to or concurrently with the payment of the issue fee and, therefore, no petition or fee is required. No new matter has been added.

Respectfully submitted,

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KLD/df/dd

Enclosures: Replacement Sheet  
Annotated Sheet Showing Changes

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